



TSU8111 具有单节充电器的双路 SP2T USB 2.0 高速开关

1 特性

- 双单刀双掷 (SP2T) USB 2.0 高速开关
 - UART 路径支持 UART 或 USB 2.0 高速信号
- 集成单节充电器
 - 集成低压降线性稳压器 (LDO)
 - 充电电压稳压精度 1%
 - 充电电流精度 8%
 - 针对壁式适配器的高达 950mA 的可编程充电电流限制
- 充电器检测符合 USB 电池充电规范 v1.1 (BCv1.1)
 - VBUS 检测
 - 数据接触侦测
 - 主和副侦测
 - 支持 USB 充电器 (DCP、CDP、SDP)
- 可在 ID 引脚上进行 5 位附件检测
 - 按附件类型自动切换
- I²C 接口
 - 手动切换功能
 - 连接和断开时产生中断
 - 支持制造中使用的控制信号 (JIG, BOOT)
- 具有过压保护功能的 VBUS 引脚的容差为 28V
- 针对输出电流控制的热调节和热关断保护
- JESD 22 ESD 性能
 - 12kV 人体模型 (VBUS/DP_CON/DM_CON/ID_CON)
 - 2kV 人体模型 (所有其他引脚)
- IEC ESD 性能
 - ±4kV 接触放电 (IEC 61000-4-2) (VBUS/DP_CON/DM_CON/ID_CON 接地 (GND))
- 浪涌保护 (VBUS/DP_CON/DM_CON/ID_CON 接地)
 - 无需使用外部元件即可保护 USB 连接器引脚

2 应用范围

- 移动电话
- 上网本/笔记本电脑
- 台式机
- 便携式手持设备

3 说明

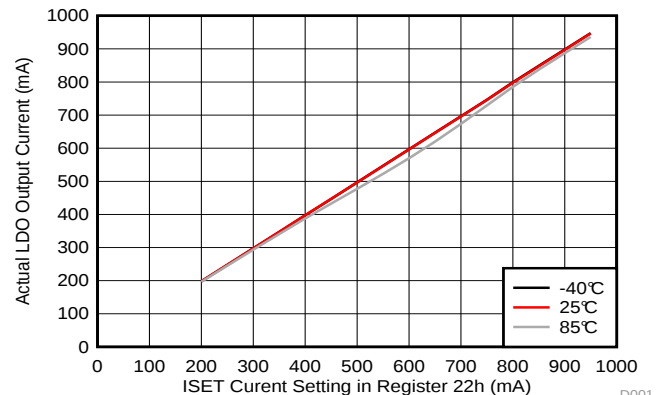
TSU8111 是一款具有集成线性充电器的双 SP2T 微型 USB 开关。由于此器件集成有充电器，因此无需配备外部充电器 IC，从而节省了成本与电路板空间。该器件可通过 USB 端口或专用充电器供电运行，并支持高达 950mA 的充电电流。连接该器件后，将通过 VBAT 或 VBUS 为其供电。TSU8111 可检测与 BCv1.1 标准兼容的充电器以及使用 ID 电阻的附件。USB 开关矩阵既可以通过自动检测来控制，也可以通过 I²C 手动进行控制。

器件信息⁽¹⁾

部件号	封装	封装尺寸 (标称值)
TSU8111	DSBGA (20)	2.14mm x 1.76mm

(1) 如需了解所有可用封装，请参见数据表末尾的可订购产品附录。

整个器件温度范围内的实际快速充电电流与寄存器电阻设置间的关系



D001



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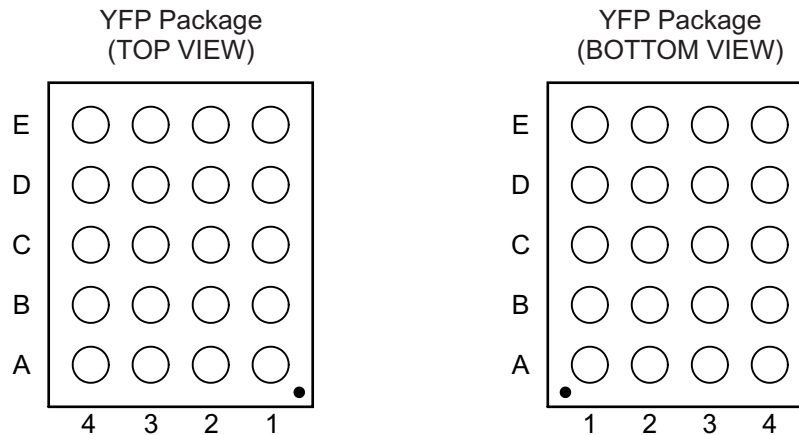
4 修订历史记录

Changes from Original (September 2012) to Revision A

Page

- 已更改 本数据表至最新的 SDS 格式并替换了所有文本、表格和图。 **1**

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
BOOT	B2	O	BOOT mode used for factory test modes. Push-pull output (active high)
DM_CON	C4	I/O	USB DM connected to USB receptacle
DM_HT	D1	I/O	USB DM on device side
DP_CON	D4	I/O	USB DP connected to USB receptacle
DP_HT	E1	I/O	USB DP on device side
GND	A2, D3	—	Ground
ID_CON	E4	I/O	USB ID connected to USB receptacle
INTB	C3	O	Interrupt to host. Push-pull output (active high)
JIG	C2	O	JIG detection used for factory test modes. Open-drain output (active low)
RxD	C1	I/O	UART Rx – capable of passing USB 2.0 HS signals
SCL	E3	I	I ² C clock
SDA	E2	I/O	I ² C data
TxD	B1	I/O	UART Tx – capable of passing USB 2.0 HS signals
VBAT	A3, B3	I	Supply voltage from battery
VBUS	A4, B4	I	Supply voltage from micro-USB connector. Charger is enabled when this supply is present.
VDDIO	D2	I	I ² C and interrupt interface logic supply voltage
VLDO	A1	O	Low dropout regulator (LDO) charger output

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

			MIN	MAX	UNIT
Supply voltage	V _{BAT}		–0.5	6	V
	V _{BUS}		–0.5	28	
	V _{DDIO}		–0.5	4.6	
Input-output terminal voltage, V _{IO}	V _{DM_CON} , V _{DP_CON} , V _{ID_CON} , V _{DP_HT} , V _{DM_HT}		–0.5	V _{BAT} + 0.5 ⁽²⁾	V
	V _{RxD} , V _{TxD}		–0.5	V _{BAT} + 0.5 ⁽²⁾	
	V _{SDA}		–0.5	4.6	
Output voltage	V _{LDO}		–0.5	6	V
	V _{JIG}		–0.5	V _{BAT} + 0.5 ⁽²⁾	
	V _{INTB} , V _{BOOT}		–0.5	4.6	
Input current	I _{BAT}			1	A
	I _{BUS}			1	
	I _K	Analog port diode current	–50	50	mA
	I _{IK}	Digital logic input clamp current	–50		
	I _{SCL}		–50	50	
Input-output terminal current, I _{IO}	I _{SDA}		–50	50	mA
	I _{IO(on)}	On-state continuous switch current	–60	60	
	I _{IO(peak)}	On-state peak switch current	–150	150	
Output current	I _{LDO}			100	mA
	I _{GND}				
	I _{INTB} , I _{BOOT}		–50	50	

- (1) Stresses beyond those listed under [Absolute Maximum Ratings](#) may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under [Recommended Operating Conditions](#). Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If V_{BUS} is present without V_{BAT}, then the absolute maximum voltage is V_{BUS} + 0.5 V, and shall not exceed 6 V in total.

6.2 Handling Ratings

				MIN	MAX	UNIT
T _{stg}	Storage temperature range			–65	150	°C
V _(ESD)	Electrostatic discharge	Human body model (HBM), stress voltage ⁽¹⁾	V _{BUS} , DP_CON, DM_CON, ID_CON	–12	12	kV
		Charged device model (CDM), stress voltage ⁽²⁾	All other pins	–2	2	
		IEC-61000-4-2 contact discharge		–4	4	kV

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage	V _{BAT}	3	4.4	V
	V _{BUS}	4	6.5	
	V _{DDIO}	1.65	3.6	
Input-output terminal voltage, V _{IO}	V _{DM_CON} , V _{DP_CON} , V _{ID_CON} , V _{DP_HT} , V _{DM_HT} , V _{RxD} , V _{TxD}	0	3.6	V
ID pin capacitance	C _{ID}		1	nF
LDO output capacitance	C _{LDO}	1		
Operating free-air temperature	T _A	–40	85	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TSU8111	UNIT
		YFP	
		20 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	70.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	0.4	
R _{θJB}	Junction-to-board thermal resistance	10.4	
Ψ _{JT}	Junction-to-top characterization parameter	1.8	
Ψ _{JB}	Junction-to-board characterization parameter	10.4	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

V_{BAT} = 3 V to 4.4 V, V_{DDIO} = 2.8 V, T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
USB and UART PATHS⁽¹⁾						
R _{ON}	On-state resistance	V _I = 0 V to 3.6 V, I _O = –2 mA, V _{BAT} = 3.6 V		8		Ω
ΔR _{ON}	On-state resistance match between channels	V _I = 0.4 V, I _O = –2 mA, V _{BAT} = 3.6 V		0.5		Ω
R _{ON(flat)}	On-state resistance flatness	V _I = 0 V to 3.6 V, I _O = –2 mA, V _{BAT} = 3.6 V		0.7		Ω
I _{IO(OFF)}	Off-state leakage current	V _I = 0.3 V, V _O = 2.7 V or V _I = 2.7 V, V _O = 0.3 V, V _{BAT} = 4.4 V, Switch off		45		nA
I _{IO(ON)}	On-state leakage current	V _I = OPEN, V _O = 0.3 V or 2.7 V, V _{BAT} = 4.4 V, Switch on		50		nA
C _{I(OFF)}	Off-state capacitance at input	DC bias = 0 V or 3.6 V, f = 10 MHz, Switch off		4		pF
C _{O(OFF)}	Off-state capacitance at output	DC bias = 0 V or 3.6 V, f = 10 MHz, Switch off		7.5		pF
C _{I(ON)}	On-state capacitance at input	DC bias = 0 V or 3.6 V, f = 10 MHz, Switch off		8.6		pF
C _{O(ON)}	On-state capacitance at output	DC bias = 0 V or 3.6 V, f = 10 MHz, Switch off		8.6		pF
BW	Bandwidth	R _L = 50 Ω, Switch on		820		MHz
O _{ISO}	Off isolation	f = 240 MHz, R _L = 50 Ω, Switch off		–36		dB
X _{TALK}	Crosstalk	f = 240 MHz, R _L = 50 Ω		–35		dB
LINEAR CHARGER⁽²⁾						
V _{CHG(OK)}	Charger input voltage OK threshold	V _{BUS} – V _{BAT}	Rising	250		mV
			Falling	45		
V _{BUS(OVP)}	VBUS over-voltage protection (default 7.5 V)	I ² C register 22h [7:6] = 00		6		V
		I ² C register 22h [7:6] = 01		6.5		
		I ² C register 22h [7:6] = 10		7		
		I ² C register 22h [7:6] = 11		7.5		

(1) V_O is equal to the asserted voltage on DP_CON and DM_CON. V_I is equal to the asserted voltage on DP_HT and DM_HT pins. I_O is equal to the current out of the DP_CON and DM_CON pins. I_I is equal to the current into the DP_HT and DM_HT pins.

(2) Fast charging current will fall below listed values when junction temperature rises above 85°C due to thermal regulation circuitry.

Electrical Characteristics (continued)

 $V_{BAT} = 3\text{ V to }4.4\text{ V}$, $V_{DDIO} = 2.8\text{ V}$, $T_A = -40^{\circ}\text{C to }85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{BUS(OVP,fail)}$	VBUS over-voltage falling threshold for restart charging			320		mV
V_{PRECHG}	Pre-charge threshold voltage			2.5		V
$V_{CHG(RST)}$	Charge restart threshold (default 100 mV)	I ² C register 20h [6:5] = 00		130		mV
		I ² C register 20h [6:5] = 01		130		
		I ² C register 20h [6:5] = 10		190		
		I ² C register 20h [6:5] = 11		240		
$V_{DO(LDO)}$	LDO dropout voltage	$V_{BUS} = 4.5\text{ V}$, $I_{LDO} = 50\text{ mA}$		150		mV
V_{LDO}	LDO output voltage	$V_{LDO} + V_{DO(LDO)} \leq V_{BUS} \leq V_{BUS(OVP)}$		4.9		V
I_{LDO}	LDO output current	$V_{LDO} = 0\text{ V}$			50	mA
I_{PRECHG}	Default pre-charge current	$V_{BAT} = 2\text{ V}$		90		mA
C_{LDO}	LDO output capacitance			1		μF
T_{PRECHG}	Pre-charge timeout			30		min
V_{SET}	Charging voltage	I ² C register 21h [3:0] = 0000		4		V
		I ² C register 21h [3:0] = 0001		4.02		
		I ² C register 21h [3:0] = 0010		4.04		
		I ² C register 21h [3:0] = 0011		4.06		
		I ² C register 21h [3:0] = 0100		4.08		
		I ² C register 21h [3:0] = 0101		4.1		
		I ² C register 21h [3:0] = 0110		4.12		
		I ² C register 21h [3:0] = 0111		4.14		
		I ² C register 21h [3:0] = 1000		4.16		
		I ² C register 21h [3:0] = 1001		4.18		
		I ² C register 21h [3:0] = 1010 (default)		4.2		
		I ² C register 21h [3:0] = 1011		4.22		
		I ² C register 21h [3:0] = 1100		4.24		
		I ² C register 21h [3:0] = 1101		4.26		
		I ² C register 21h [3:0] = 1110		4.28		
		I ² C register 21h [3:0] = 1111		4.35		
I_{SET}	Fast charging current	I ² C register 22h [3:0] = 0000		200		mA
		I ² C register 22h [3:0] = 0001		250		
		I ² C register 22h [3:0] = 0010		300		
		I ² C register 22h [3:0] = 0011		350		
		I ² C register 22h [3:0] = 0100		400		
		I ² C register 22h [3:0] = 0101 (default)		450		
		I ² C register 22h [3:0] = 0110		500		
		I ² C register 22h [3:0] = 0111		550		
		I ² C register 22h [3:0] = 1000		600		
		I ² C register 22h [3:0] = 1001		650		
		I ² C register 22h [3:0] = 1010		700		
		I ² C register 22h [3:0] = 1011		750		
		I ² C register 22h [3:0] = 1100		800		
		I ² C register 22h [3:0] = 1101		850		
		I ² C register 22h [3:0] = 1110		900		
		I ² C register 22h [3:0] = 1111		950		
		Charging current accuracy	-8%		8%	

Electrical Characteristics (continued)

 $V_{BAT} = 3\text{ V to }4.4\text{ V}$, $V_{DDIO} = 2.8\text{ V}$, $T_A = -40^{\circ}\text{C to }85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{FULL}	Full charge current	I ² C register 22h [7:4] = 0000		50		mA
		I ² C register 22h [7:4] = 0001		60		
		I ² C register 22h [7:4] = 0010		70		
		I ² C register 22h [7:4] = 0011		80		
		I ² C register 22h [7:4] = 0100		90		
		I ² C register 22h [7:4] = 0101 (default)		100		
		I ² C register 22h [7:4] = 0110		110		
		I ² C register 22h [7:4] = 0111		120		
		I ² C register 22h [7:4] = 1000		130		
		I ² C register 22h [7:4] = 1001		140		
		I ² C register 22h [7:4] = 1010		150		
		I ² C register 22h [7:4] = 1011		160		
		I ² C register 22h [7:4] = 1100		170		
		I ² C register 22h [7:4] = 1101		180		
		I ² C register 22h [7:4] = 1110		190		
		I ² C register 22h [7:4] = 1111		200		
I ² C INTERFACE (SCL and SDA)						
V _{IH}	High-level input voltage		V _{DDIO} × 0.7		V _{DDIO}	V
V _{IL}	Low-level input voltage		0		V _{DDIO} × 0.3	V
V _{OH}	High-level output voltage	I _{OH} = −3 mA	V _{DDIO} × 0.7		V _{DDIO}	V
V _{OL}	Low-level output voltage	I _{OL} = 3 mA	0		0.4	V
DIGITAL SIGNAL OUTPUTS – JIG, INTB, and BOOT						
V _{OL(JIG)}	Low-level output voltage	I _{OL} = 10 mA, V _{BAT} = 3.0 V			0.5	V
V _{OH(INTB,BOOT)}	High-level output voltage	I _{OH} = -4 mA, V _{DDIO} = 1.65 V	1.16		V _{DDIO}	V
V _{OL(INTB,BOOT)}	Low-level output voltage	I _{OL} = 4 mA, V _{DDIO} = 1.65 V	0		0.33	V
CURRENT CONSUMPTION						
I _{BAT(standby)}	VBAT standby current consumption	V _{BUS} = 0 V, idle state		27	36	μA
I _{BAT(operating)}	VBAT operating current consumption	V _{BUS} = 0 V, USB switch closed		100	150	μA
I _{BUS}	VBUS operating current consumption	V _{BUS} = 5 V, VBAT floating	0.6		0.75	mA
VOLTAGE PROTECTION						
V _{BUS(UVLO)}	V _{BUS} under voltage – upper threshold	V _{BUS} rising		2.85		V
	V _{BUS} under voltage – lower threshold	V _{BUS} falling		2.55		
V _{BUS(valid)}	V _{BUS} interrupt threshold	V _{BUS} rising		3.6		V
V _{BAT(UVLO)}	V _{BAT} under voltage – upper threshold	V _{BAT} rising		2.65		V
	V _{BAT} under voltage – lower threshold	V _{BAT} falling		2.45		

6.6 Timing Requirements

	MIN	TYP	MAX	UNIT
f_{SCL} I ² C clock frequency	64		400	kHz

6.7 Switching Characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{on} Switch turn-on time	From receipt of I ² C ACK bit		57		μs
t_{off} Switch turn-off time	From receipt of I ² C ACK bit		5.2		μs

6.8 Typical Characteristics

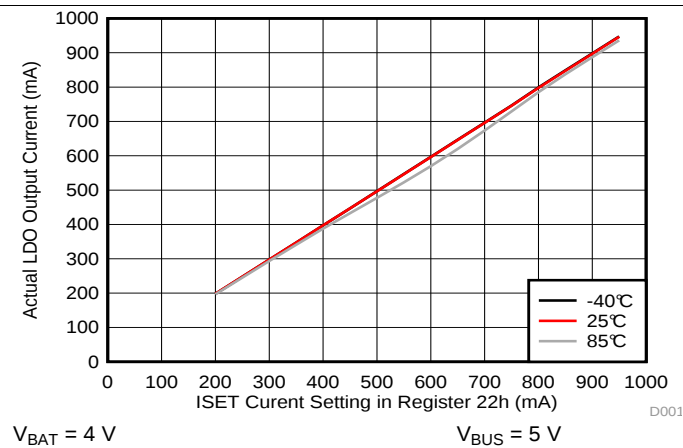


Figure 1. Actual Fast-charging Current vs Register Setting Across Device Temperature Range

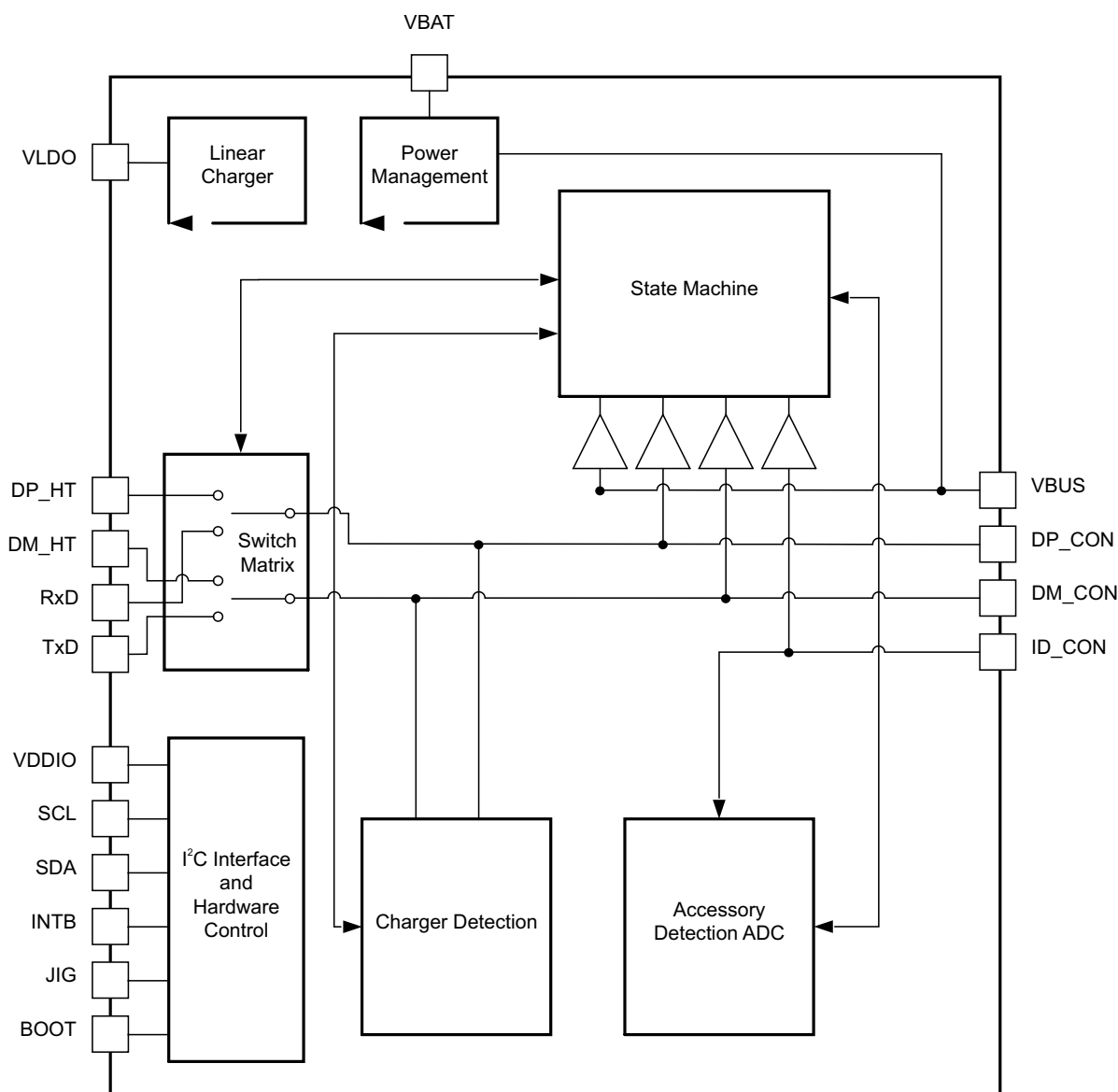
7 Detailed Description

7.1 Overview

The TSU8111 is designed to interface a portable device (PD) to external peripherals through a micro-USB connector.

The device will automatically detect accessories via the mini-USB or micro-USB 5-pin connectors. The type of accessory detected will be stored in the TSU8111's I²C registers, and can be read by the host processor. The TSU8111 has a network of USB 2.0 High Speed switches that can be automatically opened and closed based on the accessory detected. See [Automatic Switching Mode](#) for details of which switches are closed during each mode of operation. The TSU8111 also offers a manual switching mode through I²C, allowing the host processor to decide which switches will be opened and closed. The TSU8111 also provides a linear charger with a maximum programmable charging current of 950 mA.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Linear Charger

The TSU8111 has a linear battery charger with charging currents adjustable from 200 mA to 950 mA. If $3.7\text{ V} < V_{\text{BUS}} < 7.5\text{ V}$ and $V_{\text{BUS}} > V_{\text{BAT}} + 250\text{ mV}$, then the charger starts charging automatically. If $V_{\text{BAT}} < V_{\text{PRECHG}}$, the device starts with a pre-charge mode with a charging current of 90 mA. Once V_{BAT} reaches V_{PRECHG} , the device switches to fast charge mode with soft start. When V_{BAT} approaches V_{SET} , constant-voltage (CV) charging mode starts with programmed regulation voltage. At CV mode, if the charging current reaches the programmed full charge current, the TSU8111 will generate an interrupt to the host indicating a full charge and will start the charger shutoff timer. If the shutoff timer is disabled, the charger stays at CV mode until stopped by the host processor.

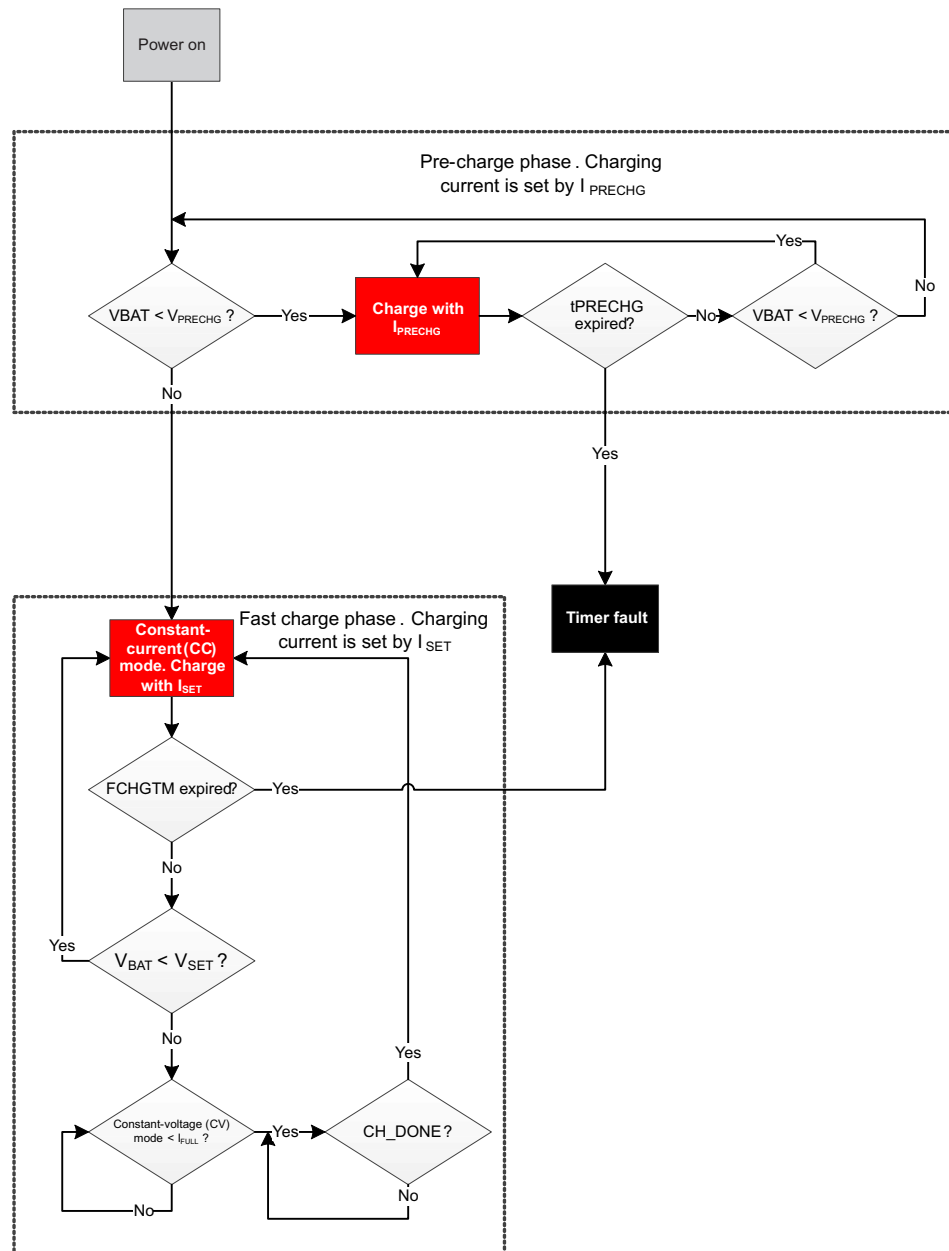


Figure 2. TSU8111 Charger Flow Chart

Feature Description (continued)

7.3.2 Voltage Protection

7.3.2.1 Overvoltage Protection

When V_{BUS} rises above $V_{BUS(OVP)}$, the linear charger is turned off, removing power from the circuit. The OVP EN interrupt bit is set high when an overvoltage condition is detected. When the input voltage returns below $V_{BUS(OVP)} - V_{BUS(OVP(hys))}$ and remains above $V_{BUS(UVLO)}$, the charger is turned on again.

7.3.2.2 Undervoltage Protection

The TSU8111 is powered off when V_{BUS} and V_{BAT} are below the lower thresholds of $V_{BUS(UVLO)}$ and $V_{BAT(UVLO)}$. When V_{BAT} rises above 2.5 V, the device will be turned on but the linear charger will remain powered off. Both the TSU8111 and the linear charger will only be turned on when $V_{BUS} > 3.7$ V and $V_{BUS} - V_{BAT} > 250$ mV.

7.3.3 Power-on Reset

When power is applied to VBAT, an internal power-on reset holds the TSU8111 in a reset condition. When V_{BAT} reaches V_{POR} , the TSU8111 I²C registers and state machine initialize to their default states.

After the initial power-up phase, V_{BAT} must be lowered below 0.2 V and then back up to V_{DDIO} to initiate a power reset cycle.

7.3.4 Software Reset

To initiate a software reset on the TSU8111, perform the steps below:

1. Hold SDA and SCL low for at least 30 ms to reset the digital logic of the TSU8111.
2. Write a 1 to bit 0 of register 1Bh. This will reset the TSU8111, and the bit will be cleared after the reset. After the reset, INTB will keep low until the INT Mask bit of register 02h is cleared.

7.3.5 Power Supervisor

The TSU8111 uses V_{BAT} as the primary supply voltage. V_{BUS} is the secondary supply. V_{DDIO} is used for I²C communication.

7.4 Device Functional Modes

7.4.1 Standby Mode

Standby mode is the default mode upon power up and occurs when no accessory is attached. During this time, the VBUS and ID lines are continually monitored through comparators to determine when an accessory is attached. If an accessory is attached, then the TSU8111 will enter either automatic or manual switching mode, depending on bit 2 in register 02h.

7.4.2 Automatic Switching Mode

The TSU8111 uses a current source and an internal comparator to detect a resistance on the ID pin. The current source creates V_{ID} on the ID pin, which is compared to a changing V_{REF} input to the comparator. An incrementing 5-bit counter increases V_{REF} until the comparator output changes. At this point, the TSU8111 latches the 5-bit counter value and determines the accessory type from [Table 1](#).

When the TSU8111 detects VBUS but no ID resistor, the TSU8111 runs charger detection on the DP and DM lines. The TSU8111 can detect chargers compatible with the USB Battery Charging Specification version 1.1 (BCv1.1). The switch status for the BCv1.1 charger types can be found at the end of [Table 1](#).

Device Functional Modes (continued)

Table 1. Accessory and Charger Detection Lookup Table

ACCESSORY	DETECTED IMPEDANCE ON ID (kΩ)	RESISTOR TOLERANCE (%)	5-BIT COUNTER ADC VALUE	SWITCH STATE		FACTORY CABLE	
				DP / DM			
				DP_HT / DM_HT	RxD / TxD	JIG	BOOT
OTG	0	N/A	00000	ON	OFF	OFF	OFF
MHL	1	5	00000	OFF	OFF	OFF	OFF
Audio Device Type 3	28.7	5	01110	OFF	OFF	OFF	OFF
Reserved Accessory #1	34	5	01111	OFF	OFF	OFF	OFF
Reserved Accessory #2	40.2	5	10000	OFF	OFF	OFF	OFF
Reserved Accessory #3	49.9	5	10001	OFF	OFF	OFF	OFF
Reserved Accessory #4	64.9	5	10010	OFF	OFF	OFF	OFF
Audio Device Type 2	80.27	5	10011	OFF	OFF	OFF	OFF
Phone Powered Device	102	5	10100	OFF	ON	OFF	OFF
TTY Converter	121	5	10101	OFF	OFF	OFF	OFF
UART Cable	150	5	10110	OFF	ON	OFF	OFF
Type 1 Charger	200	5	10111	ON	OFF	OFF	OFF
Factory Mode Cable – Boot Off USB	255	5	11000	ON	OFF	ON	OFF
Factory Mode Cable – Boot On USB	301	5	11001	ON	OFF	ON	ON
Audio / Video Cable	365	5	11010	OFF	OFF	OFF	OFF
Type 2 Charger	442	5	11011	ON	OFF	OFF	OFF
Factory Mode Cable – Boot Off UART	523	5	11100	OFF	ON	ON	OFF
Factory Mode Cable – Boot On UART	619	5	11101	OFF	ON	ON	ON
Stereo Headset with Remote (Audio Device Type 1)	1000.07	10	11110	OFF	OFF	OFF	OFF
Monio/Stereo Headset (Audio Device Type 1)	1002	10	11110	OFF	OFF	OFF	OFF
No ID	N/A	N/A	11111	OFF	OFF	OFF	OFF
USB Standard Downstream Port (SDP)	N/A	N/A	11111	ON	OFF	OFF	OFF
USB Charging Downstream Port (CDP)	N/A	N/A	11111	ON	OFF	OFF	OFF
Dedicated Charging Port (DCP)	N/A	N/A	11111	OFF	OFF	OFF	OFF

7.4.3 Manual Switching Mode

Write a 0 to bit 2 of register 02h to enable manual switching mode. The switch status of DP and DM can then be controlled by writing to register 13h [7:2]. See [Register Map](#) for details about switch status using register 13h.

7.5 Programming

The bidirectional I²C bus consists of the serial clock (SCL) and serial data (SDA) lines. Both lines must be connected to a positive supply via a pullup resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

I²C communication with this device is initiated by the master sending a START condition, a high-to-low transition on the SDA input/output while the SCL input is high (see [Figure 3](#)). After the start condition, the device address byte is sent, most significant bit (MSB) first, including the data direction bit (R/W). This device does not respond to the general call address. After receiving the valid address byte, this device responds with an ACK, a low on the SDA input/output during the high of the ACK-related clock pulse.

Programming (continued)

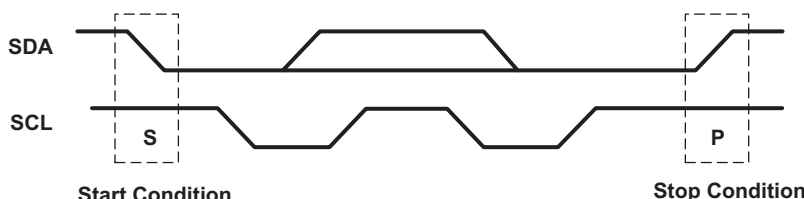


Figure 3. Definition of START and Stop Conditions

The data byte follows the address ACK. The R/W bit is kept low for transfer from the master to the slave. The data byte is followed by an ACK sent from this device. Data are the output only if complete bytes are received and acknowledged. The output data is valid at time tpv after the low-to-high transition of SCL, during the clock cycle for the ACK.

On the I²C bus, only one data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high pulse of the clock period, as changes in the data line at this time are interpreted as control commands (START or STOP). See [Figure 4](#).

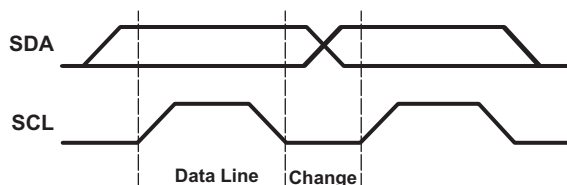


Figure 4. Bit Transfer

A STOP condition, a low-to-high transition on the SDA input/output while the SCL input is high, is sent by the master (see [Figure 3](#)).

The number of data bytes transferred between the START and STOP conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one ACK bit. The transmitter must release the SDA line before the receiver can send an ACK bit.

A slave receiver that is addressed must generate an ACK after the reception of each byte. The device that acknowledges has to pull down the SDA line during the ACK clock pulse so that the SDA line is stable low during the high pulse of the ACK-related clock period (see [Figure 5](#)). Setup and hold times must be taken into account.

Programming (continued)

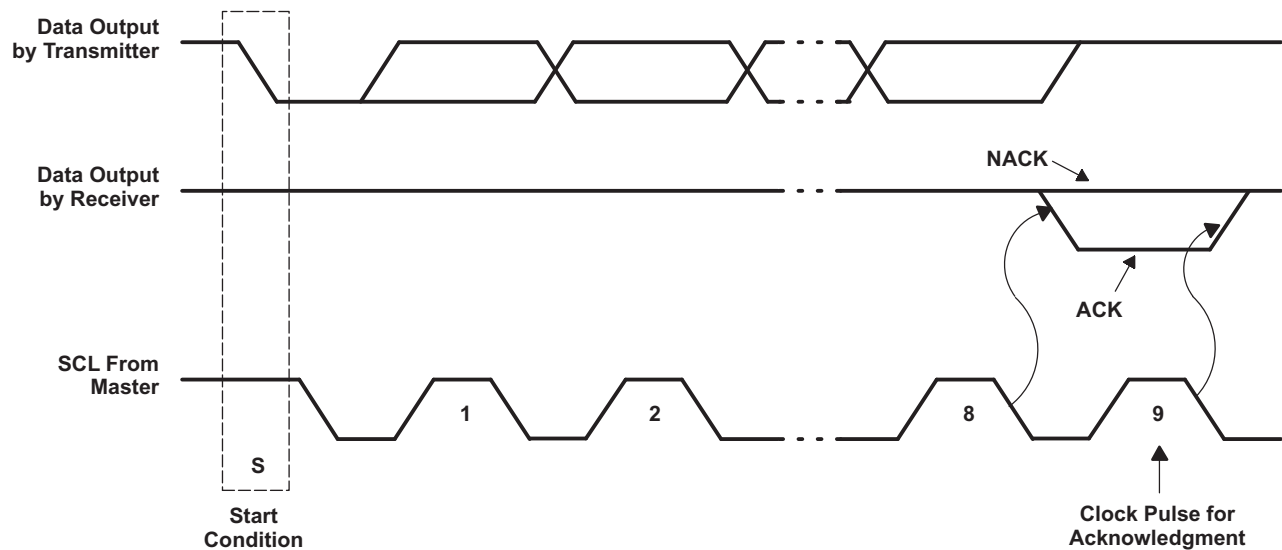


Figure 5. Acknowledgement on I2C Bus

7.5.1 Writes

Data is transmitted to the TSU8111 by sending the device slave address and setting the LSB to a logic 0 (see [Figure 6](#) for device address). The command byte is sent after the address and determines which register receives the data that follows the command byte. The next byte is written to the specified register on the rising edge of the ACK clock pulse.

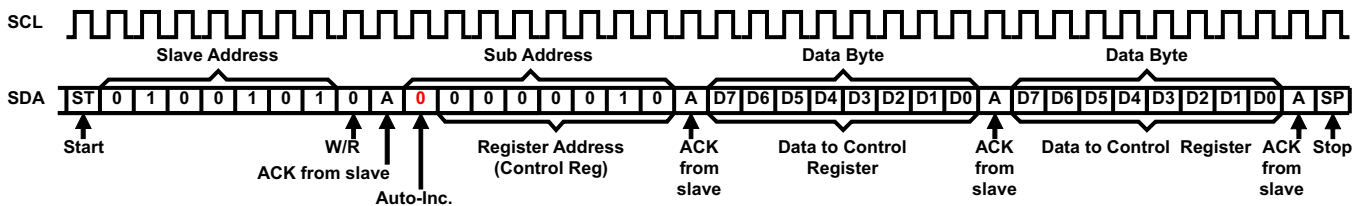


Figure 6. Repeated Data Write to a Single Register

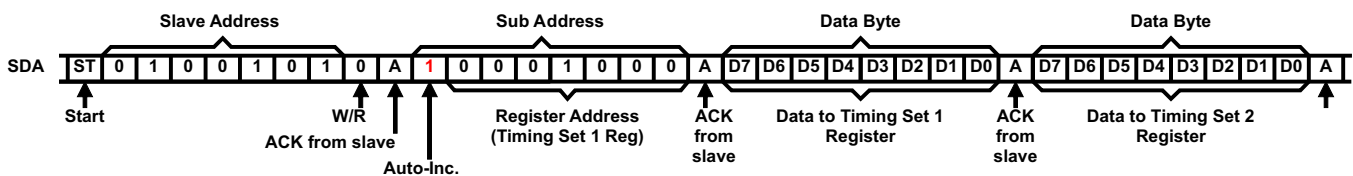


Figure 7. Burst Data Write to Multiple Registers

7.5.2 Reads

The bus master must first send the TSU8111 slave address with the LSB set to logic 0. The command byte is sent after the address and determines which register is accessed. After a restart, the device slave address is sent again but, this time, the LSB is set to logic 1. Data from the register defined by the command byte then is sent by the TSU8111. Data is clocked into the SDA output shift register on the rising edge of the ACK clock pulse, see [Figure 8](#).

Programming (continued)

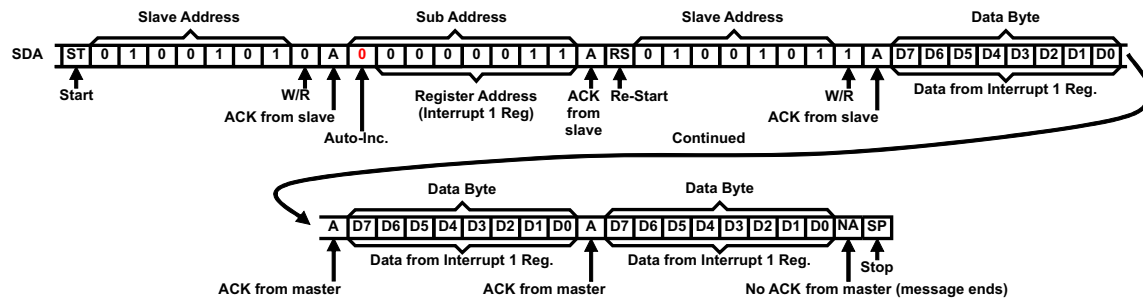


Figure 8. Repeated Data Read from a Single Register – Combined Mode

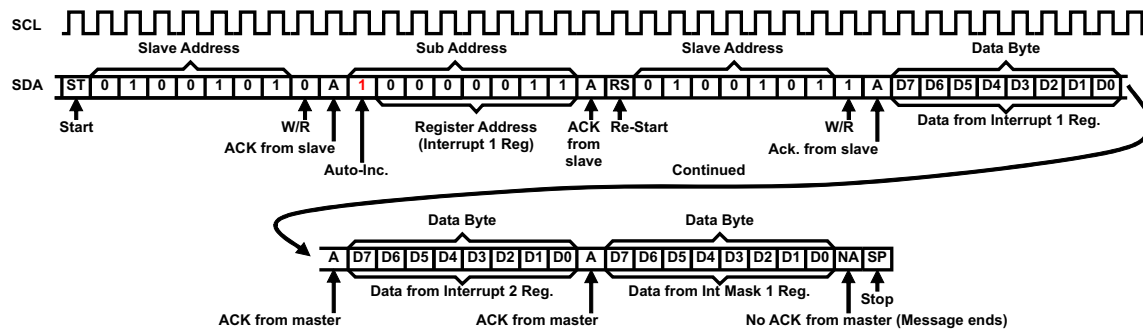


Figure 9. Burst Data Read from Multiple Registers – Combined Mode

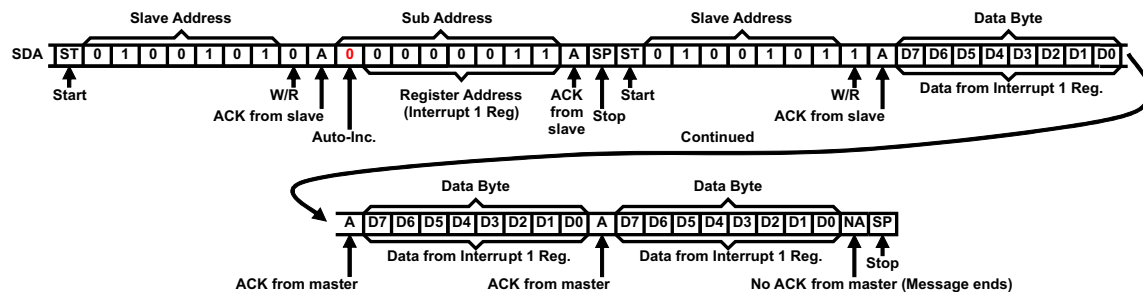


Figure 10. Repeated Data Read from a Single Register – Split Mode

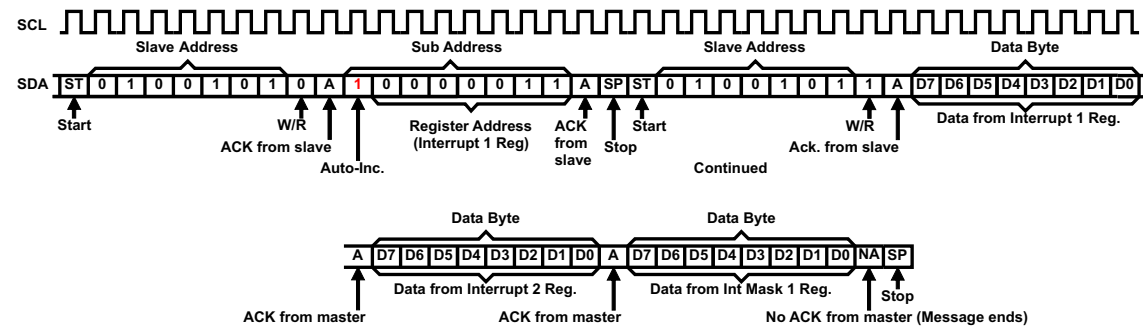


Figure 11. Burst Data Read from Multiple Registers – Split Mode

Programming (continued)

Additional notes on I²C interface:

1. SDA is pulled low on ACK from either the slave or the master.
2. Register writes always require sub-address writes before the first data byte.
3. Repeated data writes to a single register continue indefinitely until stop or restart.
4. Repeated data reads from a single register continue indefinitely until no ACK from master.
5. Burst data writes start at the specified register address, then advance to the next register address, even to the read-only registers. For these registers, data write appears to occur, though no data are changed by the writes. After register 14h is written, writing resumes to register 01h and continues until stop or restart.
6. Burst data reads start at the specified register address, then advance to the next register address. Once register 14h is read, reading resumes from register 01h and continues until no ACK from master.

7.6 Register Map⁽¹⁾⁽²⁾

(1) Write "0" to the blank register bits.

(2) Values read from the blank register bits are invalid and undefined.

ADDR	REGISTER	TYPE	RESET VALUE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	
01h	Device ID	R	1011010	Version ID					Vendor ID			
02h	Control	R/W	xxx11111				Switch Open	Raw Data	Manual Sw.	Wait	INT Mask	
03h	Interrupt 1	R	x0000000		VBUS	OVP EN	LKR	LKP	KP	Detach	Attach	
04h	Interrupt 2	R	x0000000		OTP EN	CONNECT	Stuck Key RCV	Stuck Key	ADC Change	Reserved Attach	A/V Charging	
05h	Interrupt Mask 1	R/W	x0000000		VBUS	OVP EN	LKR	LKP	KP	Detach	Attach	
06h	Interrupt Mask 2	R/W	x0000000		OTP EN	CONNECT	Stuck Key RCV	Stuck Key	ADC Change	Reserved Attach	Charging A/V	
07h	ADC	R	xxx11111				ADC Value					
08h	Timing Set 1	R/W	0	Key Press				Device Wake Up				
09h	Timing Set 2	R/W	0	Switching Wait				Long Key Press				
0Ah	Device Type 1	R	0	USB OTG	DCP	CDP	Type 1 / Type 2 charger	UART	USB	VBUS	MHL	
0Bh	Device Type 2	R	0	Audio Type 3	Audio / Video	TTY	PPD	JIG UART OFF	JIG UART ON	JIG USB OFF	JIG USB ON	
0Ch	Button 1	R	0	7	6	5	4	3	2	1	Send End	
0Dh	Button 2	R	x0000000		Unknown	Error	12	11	10	9	8	
13h	Manual SW 1	R/W	000000xx	DM Switching			DP Switching					
14h	Manual SW 2	R/W	xxxx00xx					BOOT SW	JIG ON			
1Bh	Reset	W	11111111								Reset	
20h	Charger Control 1	R/W	11000	CH DIS	CHRSTTH		CHENOV	FCMEN		FCHGTM		
21h	Charger Control 2	R/W	11010	IFULL				CV SET				
22h	Charger Control 3	R/W	11010101	OVPV		AUTOSTOP	ISET L	ISET				
24h	Charger Interrupt	R	xx0xxxxx			CH FAULT	CH DONE	CH CV	CH FC	CH PC	CH IDLE	
25h	Charger Interrupt Mask	R/W	xx0xxxxx			CH FAULT	CH DONE	CH CV	CH FC	CH PC	CH IDLE	
26h	Charger Status	R	xx0xxxxx	FTE	PTE	CH FAULT	CH DONE	CH CV	CH FC	CH PC	CH IDLE	

7.6.1 Device ID (01h) Register Field Descriptions

Table 2. Device ID (01h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	Version ID	R	01011	Unique identifier for chip version (01011)
2-0	Vendor ID	R	010	Unique identifier 010 for Texas Instruments

7.6.2 Control (02h) Register Field Descriptions

Table 3. Control (02h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	Blank	N/A	N/A	N/A
4	Switch Open	R/W	1	0: Open all switches 1: Automatic switching by accessory detection
3	Raw Data	R/W	1	0: Continue reading ID pin resistance after impedance has been detected 1: When ID resistance is connected, do not run ID detection again until the next attach/detach
2	Manual Sw.	R/W	1	0: Manual switching mode enabled and controlled by register 13h 1: Automatic switching by accessory detection
1	Wait	R/W	1	0: Wait until host resets this bit high 1: Wait until switching timer has expired
0	INT Mask	R/W	1	0: Unmask interrupt 1: Mask interrupt

7.6.3 Interrupt 1 (03h) Register Field Descriptions

Table 4. Interrupt 1 (03h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	Unused	N/A	N/A	N/A
6	VBUS	R/Clr	0	1: VBUS detected
5	OVP EN	R/Clr	0	1: Overvoltage detected
4	LKR	R/Clr	0	1: Long key release
3	LKP	R/Clr	0	1: Long key press
2	KP	R/Clr	0	1: Key press
1	Detach	R/Clr	0	1: Accessory detach detected
0	Attach	R/Clr	0	1: Accessory attach detected

7.6.4 Interrupt 2 (04h) Register Field Descriptions

Table 5. Interrupt 2 (04h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	Unused	N/A	N/A	N/A
6	OTP EN	R	0	1: Over-temperature protection enabled
5	Connect	R	0	1: Switch is connected (closed)
4	Stuck Key RCV	R	0	1: Stuck key is recovered
3	Stuck Key	R	0	1: Stuck key is detected
2	ADC_Change	R	0	1: ADC value is changed when Raw Data is enabled
1	Reserved_Attach	R	0	1: Reserved device is attached
0	A/V_Charging	R	0	1: Charger detected when A/V cable is attached

7.6.5 Interrupt Mask 1 (05h) Register Field Descriptions

Table 6. Interrupt Mask 1 (05h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	Unused	N/A	N/A	N/A
6	VBUS	R/W	0	0: Unmask VBUS interrupt 1: Mask VBUS interrupt
5	OVP EN	R/W	0	0: Unmask OVP EN interrupt 1: Mask OVP EN interrupt
4	LKR	R/W	0	0: Unmask long key release interrupt 1: Mask long key release interrupt
3	LKP	R/W	0	0: Unmask long key press interrupt 1: Mask long key press interrupt
2	KP	R/W	0	0: Unmask key press interrupt 1: Mask key press interrupt
1	Detach	R/W	0	0: Unmask detach interrupt 1: Mask detach interrupt
0	Attach	R/W	0	0: Unmask attach interrupt 1: Mask attach interrupt

7.6.6 Interrupt Mask 2 (06h) Register Field Descriptions

Table 7. Interrupt Mask 2 (06h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	Unused	R/W	N/A	N/A
6	OTP EN	R/W	0	0: Unmask OTP EN interrupt 1: Mask OTP EN interrupt
5	Connect	R/W	0	0: Unmask connect interrupt 1: Mask connect interrupt
4	Stuck Key	R/W	0	0: Unmask Stuck Key RCV interrupt 1: Mask Stuck Key RCV interrupt
3	Stuck Key	R/W	0	0: Unmask Stuck Key interrupt 1: Mask Stuck Key interrupt
2	ADC Change	R/W	0	0: Unmask ADC Change interrupt 1: Mask ADC Change interrupt
1	Reserved	R/W	0	0: Unmask Reserved Attach interrupt 1: Mask Reserved Attach interrupt
0	A/V Charging	R/W	0	0: Unmask A/V Charging interrupt 1: Mask A/V Charging interrupt

7.6.7 ADC (07h) Register Field Descriptions

Table 8. ADC (07h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	Reserved	R	N/A	N/A
4-0	ADC value	R	11111	5-bit ADC counter value latched after accessory detection on ID pin

7.6.8 Timing Set 1 (08h) Register Field Descriptions

Table 9. Timing Set 1 (08h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	Key press	R/W	0000	Normal key press duration 0000: 100 ms 0001: 200 ms 0010: 300 ms 0011: 400 ms 0100: 500 ms 0101: 600 ms 0110: 700 ms 0111: 800 ms 1000: 900 ms 1001: 1000 ms Any other value: invalid
3-0	Device wake up	R/W	0000	Device wake up duration 0000: 50 ms 0001: 100 ms 0010: 150 ms 0011: 200 ms 0100: 300 ms 0101: 400 ms 0110: 500 ms 0111: 600 ms 1000: 700 ms 1001: 800 ms 1010: 900 ms 1011: 1000 ms Any other value: invalid

7.6.9 Timing Set 2 (09h) Register Field Descriptions

Table 10. Timing Set 2 (09h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	Switching wait	R/W	0000	Wait time between detection complete and switching 0000: 10 ms 0001: 30 ms 0010: 50 ms 0011: 70 ms 0100: 90 ms 0101: 110 ms 0110: 130 ms 0111: 150 ms 1000: 170 ms 1001: 190 ms 1010: 210 ms Any other value: invalid

Table 10. Timing Set 2 (09h) Register Field Descriptions (continued)

Bit	Field	Type	Reset	Description
3-0	Long key press	R/W	0000	Long key press duration 0000: 300 ms 0001: 400 ms 0010: 500 ms 0011: 600 ms 0100: 700 ms 0101: 800 ms 0110: 900 ms 0111: 1000 ms 1000: 1100 ms 1001: 1200 ms 1010: 1300 ms 1011: 1400 ms 1100: 1500 ms Any other value: invalid

7.6.10 Device Type 1 (0Ah) Register Field Descriptions

Table 11. Device Type 1 (0Ah) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	USB OTG	R	0	USB on-the-go (OTG) device
6	DCP	R	0	Dedicated charging port
5	CDP	R	0	Charging downstream port
4	Type1/Type2 charger	R	0	Type 1 / Type 2 charger
3	UART	R	0	UART
2	USB	R	0	USB host
1	VBUS	R	0	VBUS valid
0	MHL	R	0	MHL device

7.6.11 Device Type 2 (0Bh) Register Field Descriptions

Table 12. Device Type 2 (0Bh) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	Audio Type 3	R	0	Audio type 3 cable
6	Audio / Video	R	0	Audio / video cable
5	TTY	R	0	TTY converter
4	PPD	R	0	Phone-powered device
3	JIG UART OFF	R	0	Factory mode cable
2	JIG UART ON	R	0	Factory mode cable
1	JIG USB OFF	R	0	Factory mode cable
0	JIG USB ON	R	0	Factory mode cable

7.6.12 Button 1 (0Ch) Register Field Descriptions

Table 13. Button 1 (0Ch) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	7	R	0	Number 7 key is pressed
6	6	R	0	Number 6 key is pressed
5	5	R	0	Number 5 key is pressed
4	4	R	0	Number 4 key is pressed
3	3	R	0	Number 3 key is pressed
2	2	R	0	Number 2 key is pressed
1	1	R	0	Number 1 key is pressed
0	Send End	R	0	Send End key is pressed

7.6.13 Button 2 (0Dh) Register Field Descriptions

Table 14. Button 2 (0Dh) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	Unused	N/A	N/A	N/A
6	Unknown	R	0	Unknown key is pressed
5	Error	R	0	Error key is pressed
4	12	R	0	Number 12 key is pressed
3	11	R	0	Number 11 key is pressed
2	10	R	0	Number 10 key is pressed
1	9	R	0	Number 9 key is pressed
0	8	R	0	Number 8 key is pressed

7.6.14 Manual SW 1 (13h) Register Field Descriptions

Table 15. Manual SW 1 (13h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	DM switching	R/W	000	000: Open all switches 001: DM is connected to DM_HT 010: Open all switches 011: DM is connected to TxD Any other value: invalid
4-2	DP switching	R/W	000	000: Open all switches 001: DP is connected to DP_HT 010: Open all switches 011: DP is connected to RxD Any other value: invalid
1-0	Unused	N/A	N/A	N/A

7.6.15 Manual SW 2 (14h) Register Field Descriptions

Table 16. Manual SW 2 (14h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	Unused	N/A	N/A	N/A
3	BOOT SW	R/W	0	0: Low 1: High
2	JIG ON	R/W	0	0: High impedance 1: GND
1-0	Unused	N/A	N/A	N/A

7.6.16 Reset (1Bh) Register Field Descriptions

Table 17. Reset (1Bh) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	Unused	N/A	N/A	N/A
0	Reset	W	0	1: Write this value (1) to reset the device. 0: Set to this value (0) after reset completed.

7.6.17 Charger control 1 (20h) Register Field Descriptions

Table 18. Charger control 1 (20h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	CH DIS	R/W	0	Force charger disable 0: Normal charger operation mode 1: Disable charger. Override charger detection and CHENOV
6-5	CHRSTTH	R/W	0	Charging restart threshold voltage 00: 130 mV 01: 130 mV 10: 190 mV 11: 240mV
4	CHENOV	R/W	1	Charger enabled override 0: Charger enabled is controlled by charger detection. Charger is enabled is DCP, CDP, or Carkit charger is detected. 1: Charge is always enabled.
3	FCMEN	R/W	1	Fast charge mode enable. Device should be in pre-charge before setting FCMEN = 0 to disable Fast Charge mode. 0: Fast charge mode is disabled. Charger remains in pre-charge mode. 1: Enable fast charge mode.
2	Unused	N/A	N/A	N/A
1-0	FCHGTM	R/W	0	Fast charge timer – These bits control the maximum amount of time that the charger will spend in fast charge mode. If the timer is over this time, FTE is changed to 1. 00: 5 hours 01: 6 hours 10: 7 hours 11: Disable fast charge timer

7.6.18 Charger control 2 (21h) Register Field Descriptions

Table 19. Charger control 2 (21h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	IFULL		0001	Charge done current threshold level 0000: 50 mA 0001: 60 mA 0010: 70 mA 0011: 80 mA 0100: 90 mA 0101: 100 mA 0110: 110 mA 0111: 120 mA 1000: 130 mA 1001: 140 mA 1010: 150 mA 1011: 160 mA 1100: 170 mA 1101: 180 mA 1110: 190 mA 1111: 200 mA

Table 19. Charger control 2 (21h) Register Field Descriptions (continued)

Bit	Field	Type	Reset	Description
3-0	CV SET		1010	Constant voltage mode voltage - in fast charge mode, when the battery voltage reaches this value, the charger transitions from fast charge mode to constant voltage charge mode. 0000: 4.00 V 0001: 4.02 V 0010: 4.04 V 0011: 4.06 V 0100: 4.08 V 0101: 4.10 V 0110: 4.12 V 0111: 4.14 V 1000: 4.16 V 1001: 4.18 V 1010: 4.20 V 1011: 4.22 V 1100: 4.24 V 1101: 4.26 V 1110: 4.28 V 1111: 4.35 V

7.6.19 Battery Charger Control 3 (22h) Register Field Descriptions

Table 20. Battery Charger Control 3 (22h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	OVP	R/W	0011	These bits set the overvoltage protection threshold. 00: 6.0 V 01: 6.5 V 10: 7.0 V 11: 7.5 V
5	AUTOST OP	R/W	0000	Auto charging stop 0: Disable charging shutoff and keep CV mode 1: Enable charging shutoff after 30-minute timer
4	ISSET L	R/W	0001	This bit is used in conjunction with ISET[3:0], and it determines the fast charge mode current limit. 0: 90 mA 1: 200 mA to 950 mA
3-0	ISSET	R/W	0101	This sets the fast charge mode current. 0000: 200 mA 0001: 250 mA 0010: 300 mA 0011: 350 mA 0100: 400 mA 0101: 450 mA 0110: 500 mA 0111: 550 mA 1000: 600 mA 1001: 650 mA 1010: 700 mA 1011: 750 mA 1100: 800 mA 1101: 850 mA 1110: 900 mA 1111: 950 mA

7.6.20 Charger Interrupt (24h) Register Field Descriptions

Table 21. Charger Interrupt (24h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	Unused	N/A	0	Always reads 0
5	CH Fault	R/Clr	0	1: Charger in fault state
4	CH DONE	R/Clr	0	1: Charge complete / top-off mode
3	CH CV	R/Clr	0	1: Charger state in constant voltage (CV) mode
2	CH FC	R/Clr	0	1: Charger state in fast charge mode (constant current)
1	CH PC	R/Clr	0	1: Charger state in pre-charge mode
0	CH IDLE	R/Clr	0	1: Charge state idle

7.6.21 Charger Interrupt Mask (25h) Register Field Descriptions

Table 22. Charger Interrupt Mask (25h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	Unused	N/A	0	Always reads 0
5	CH_Fault	R/W	0	0: Unmask CH Fault interrupt 1: Mask CH Fault interrupt
4	CH_DONE	R/W	0	0: Unmask CH Done interrupt 1: Mask CH Done interrupt
3	CH_CV	R/W	0	0: Unmask CH CV interrupt 1: Mask CH CV interrupt
2	CH_FC	R/W	0	0: Unmask CH FC interrupt 1: Mask CH FC interrupt
1	CH_PC	R/W	0	0: Unmask CH PC interrupt 1: Mask CH PC interrupt
0	CH_IDLE	R/W	0	0: Unmask CH IDLE interrupt 1: Mask CH IDLE interrupt

7.6.22 Charger Status (26h) Register Field Descriptions

Table 23. Charger Status (26h) Register Field Descriptions

Bit	Field	Type	Reset	Description
7	FTE	R/W	0	Fast charge timer expired interrupt 0: Timer not expired 1: 30-minute fast charge timer expired. Charge disabled. Restart when re-attaching charger or toggling CHENOV.
6	PTE	R/W	0	Pre-charge timer expired interrupt 0: Timer not expired 1: 30-minute pre-charge timer has expired. Charger disabled. Restart when re-attaching charger or toggling CHENOV.
5	CH Fault	R/W	0	1: Charger fault other than PTE or FTE
4	CH Done	R/W	0	1: Charge complete / top-off mode
3	CH CV	R/W	0	1: Charger state in constant voltage mode
2	CH FC	R/W	0	1: Charge state in fast charge mode (constant current)
1	CH PC	R/W	0	1: Charger state in pre-charge mode
0	CH IDLE	R/W	0	1: Charge state in idle (not charging)

8 Application and Implementation

8.1 Application Information

The TSU8111 device can be used in portable device (PD) applications for interfacing the PD with external peripherals. The TSU8111 is ideal for use when a PD needs two separate USB signal paths, accessory detection, charger detection, and a battery charging IC.

8.2 Typical Application

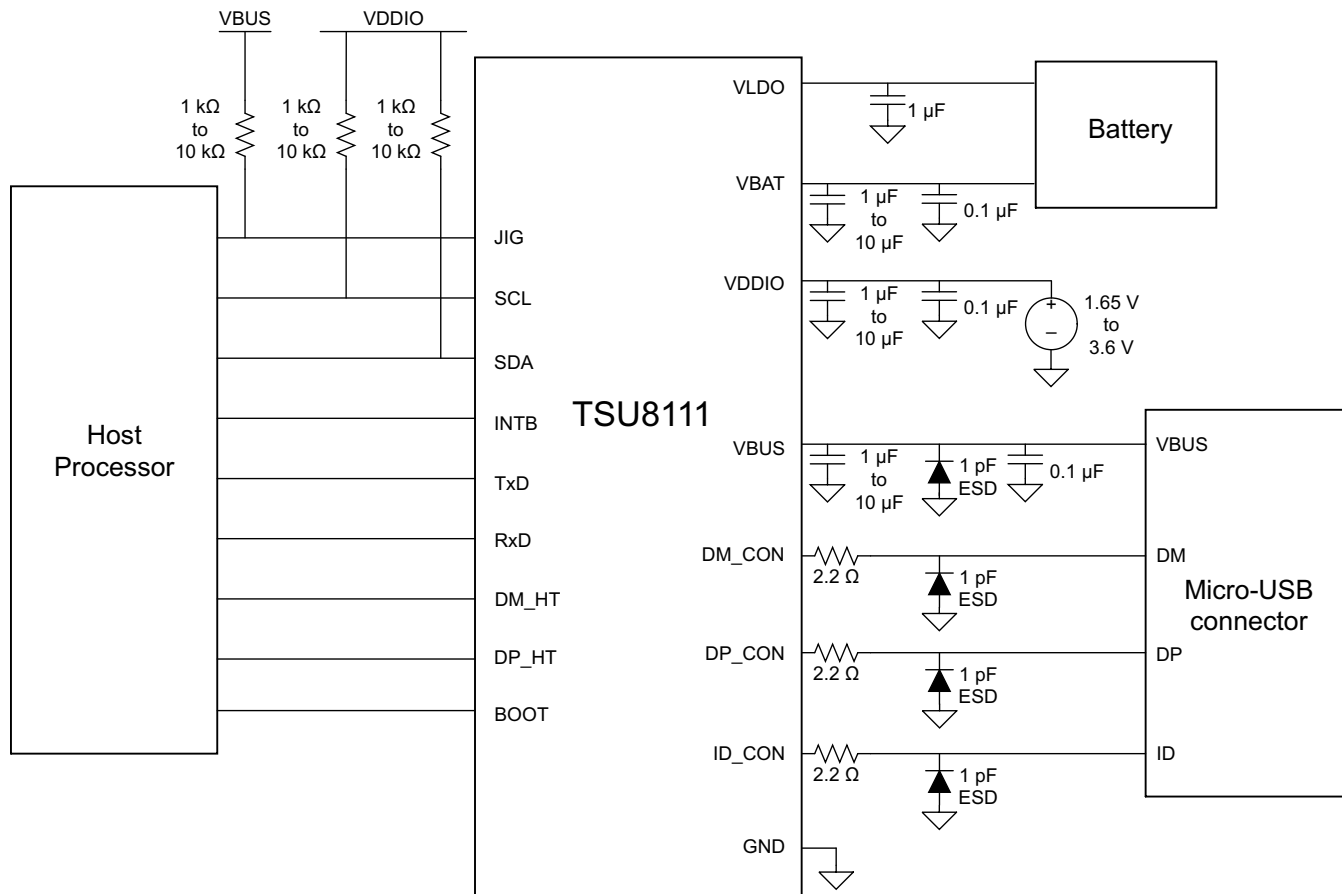


Figure 12. Interface from Host Processor to USB Connector and Battery

8.2.1 Design Requirements

For this design example, use the parameters listed in [Table 24](#).

Table 24. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
V _{BAT}	3 V to 4.4 V
V _{BUS}	4 V to 6.5 V
V _{DDIO}	1.65 V to 3.6 V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Desired ESD protection on micro-USB signal lines
 - Addition of optional 1-pF ESD diodes on the USB lines protects against ± 8 -kV IEC-61000-4-2 contact discharge. The optional 2.2- Ω resistors provide additional protection for the internal circuitry near the USB inputs.
- Output current on LDO
 - Use the charging specifications for the Li-Ion or Li-Polymer battery to determine the desired output current register setting for the TSU8111 LDO.

8.2.3 Application Curves

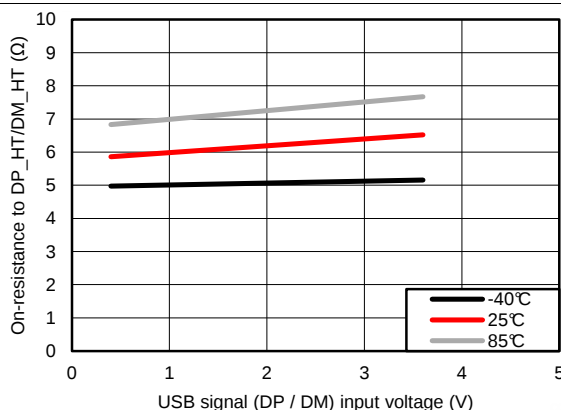


Figure 13. USB Signal vs On-resistance

9 Power Supply Recommendations

The TSU8111 has three different power supply input pins: VBAT, VBUS, and VDDIO. VBAT is the primary supply and accepts any voltage between -0.5 V and 6 V, but the operating voltage is between 3 V and 4.4 V. VBUS is the secondary power supply from the micro-USB connector and accepts any voltage between -0.5 V and 28 V, but the operating voltage is between 4 V and 6.5 V. VDDIO is the supply for I²C communication and accepts any voltage between -0.5 V and 4.6 V, but the operating voltage is between 1.65 V and 3.6 V.

The VBAT and VBUS pins each require a 0.1- μ F and a 1- μ F to 10- μ F decoupling capacitor. The 0.1- μ F capacitor smooths out high frequency noise and has a lower series inductance. The 1- μ F to 10- μ F capacitor smooths out lower frequency noise and has a much higher series inductance. Placing both capacitors near each power supply input will provide better load regulation across the frequency spectrum.

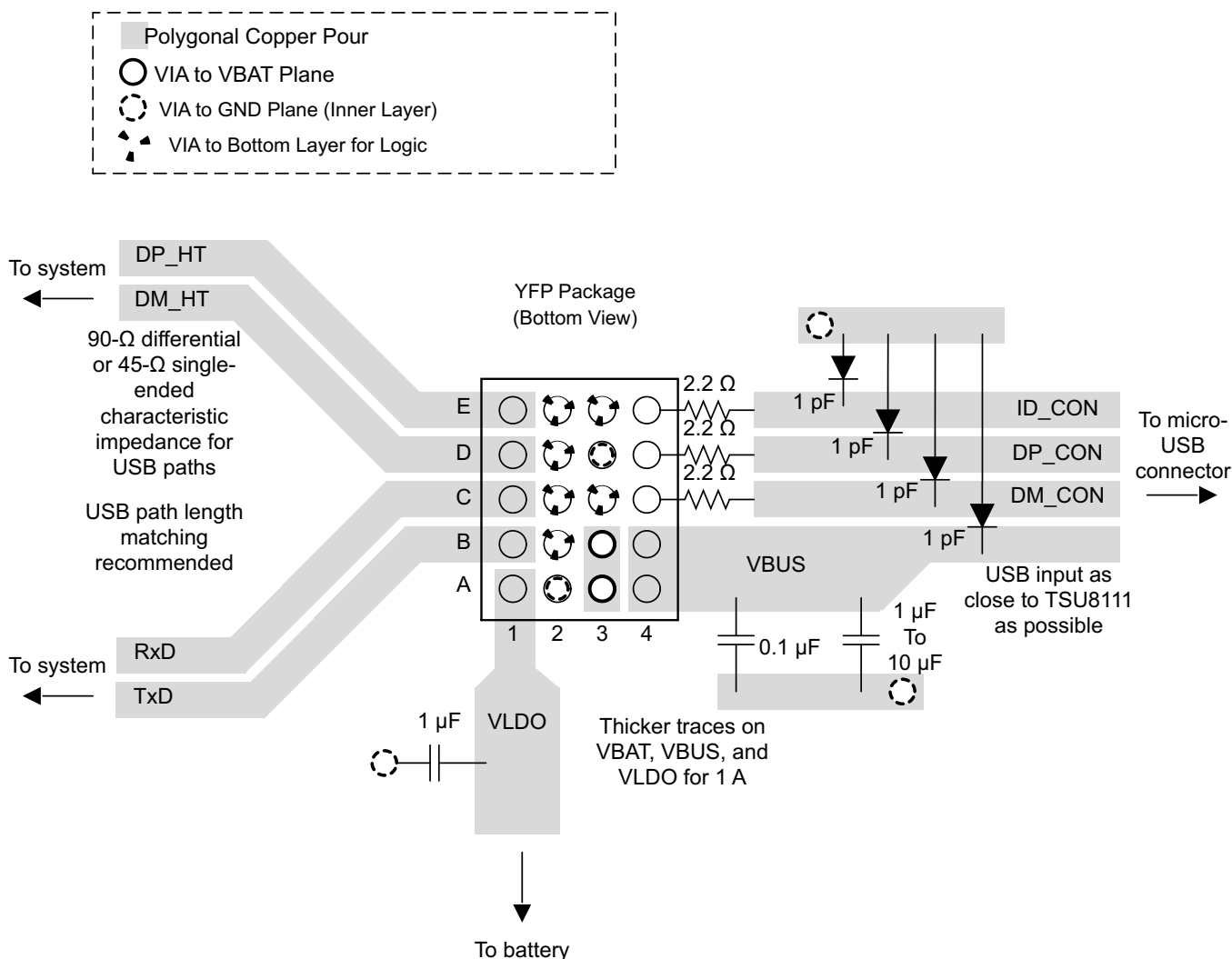
The VLDO pin requires a 1- μ F load capacitor.

10 Layout

10.1 Layout Guidelines

- The TSU8111 should be placed as close to the USB connector as possible to reduce the effect of stray noise.
- Decoupling capacitors, as mentioned in [Power Supply Recommendations](#), should be as close to the device as possible. This will also reduce the effect of ESR and ripple seen on voltages due to transient spikes.
- Lengths of all traces should be kept less than 2 inches.
- For 1-oz copper thickness, the width of the USB traces should be at least 15 mils.
- Traces to the VBAT, VBUS, and VLDO pins should be capable of carrying 1 A. This will keep routing resistance less than 100-mΩ and minimize voltage drops when charging with high currents.
- Maximize the use of vias on VBUS, VBAT, and GND. Increasing the number of vias will reduce routing resistance and improve thermal performance.
- Minimize the use of vias for USB traces to preserve USB signal integrity.
- All USB traces (DP_CON, DM_CON, DP_HT, DM_HT, TxD, and RxD) should have 45-Ω single-ended impedance and 90-Ω differential impedance to fulfill USB 2.0 requirements.

10.2 Layout Example



11 器件和文档支持

11.1 Trademarks

All trademarks are the property of their respective owners.

11.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.3 术语表

[SLYZ022](#) — *TI* 术语表。

这份术语表列出并解释术语、首字母缩略词和定义。

12 机械封装和可订购信息

以下页中包括机械封装和可订购信息。 这些信息是针对指定器件可提供的最新数据。 这些数据会在无通知且不对本文档进行修订的情况下发生改变。 欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TSU8111YFPR	ACTIVE	DSBGA	YFP	20	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A8	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

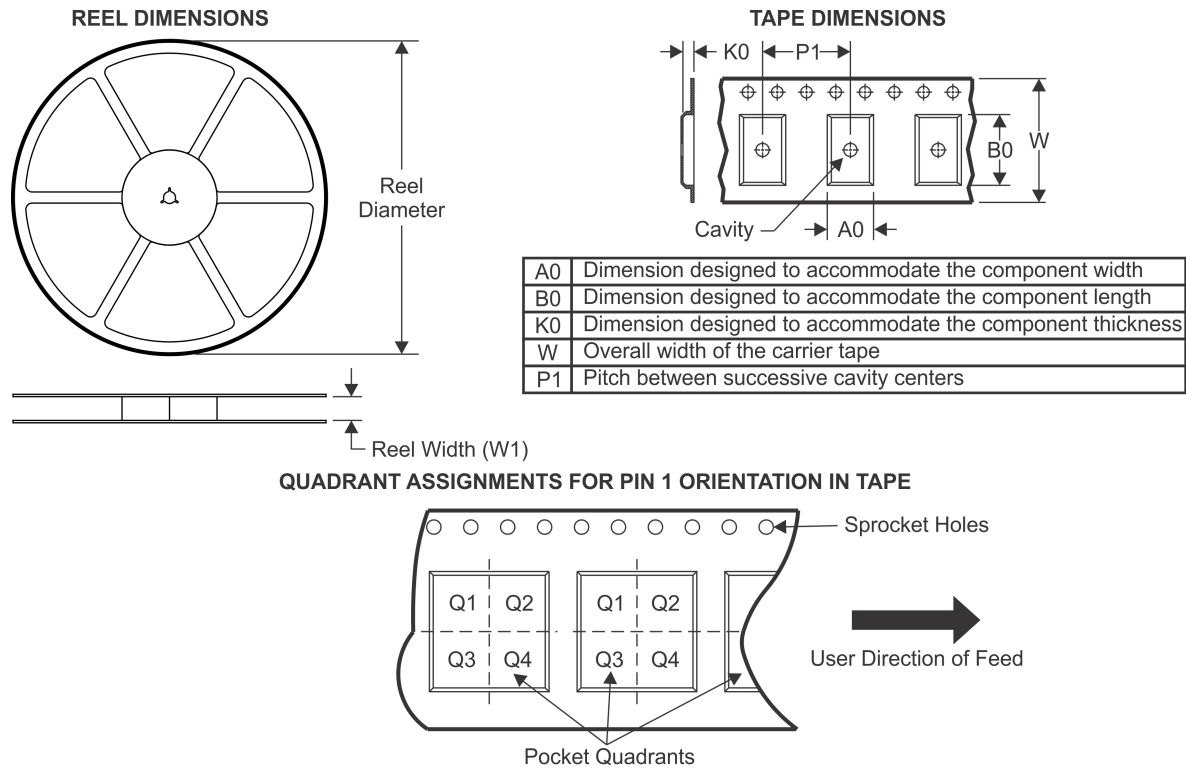
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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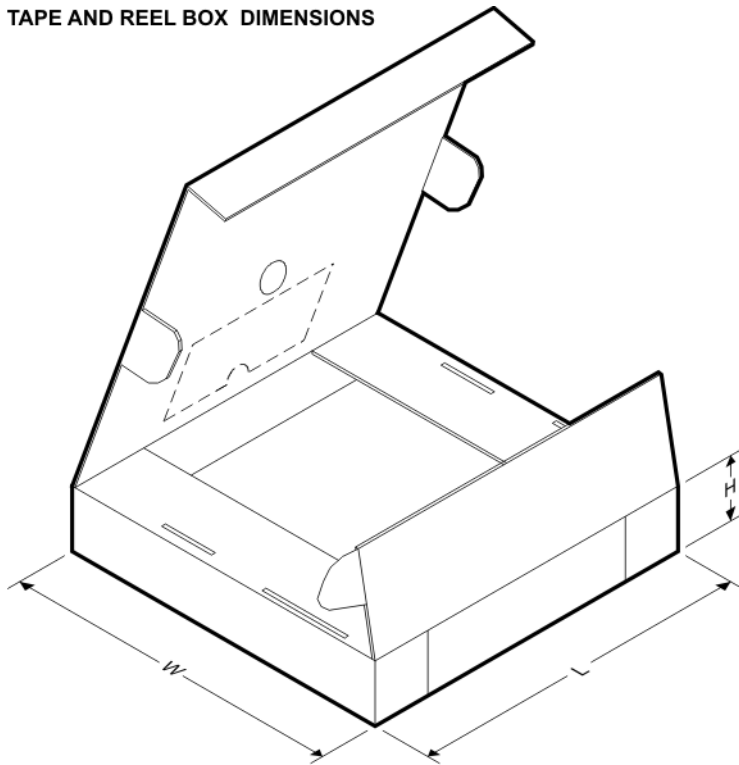
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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TSU8111YFPR	DSBGA	YFP	20	3000	180.0	8.4	1.92	2.3	0.56	4.0	8.0	Q1

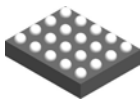
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TSU8111YFPR	DSBGA	YFP	20	3000	182.0	182.0	20.0

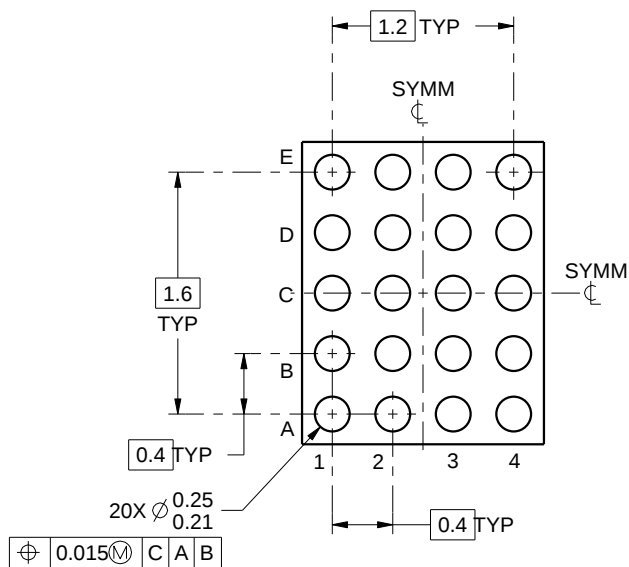
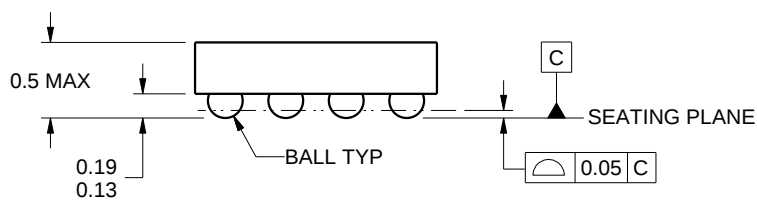
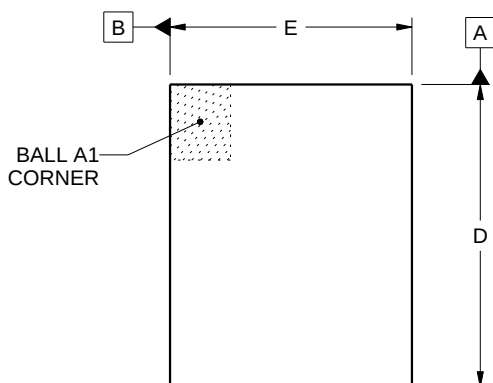
YFP0020



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



D: Max = 2.236 mm, Min = 2.176 mm

E: Max = 1.856 mm, Min = 1.796 mm

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NOTES:

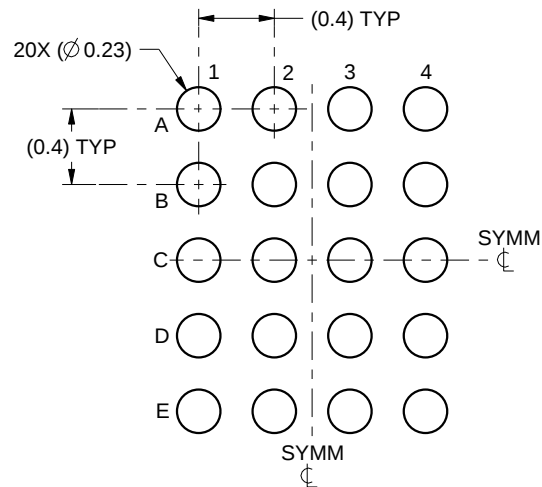
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

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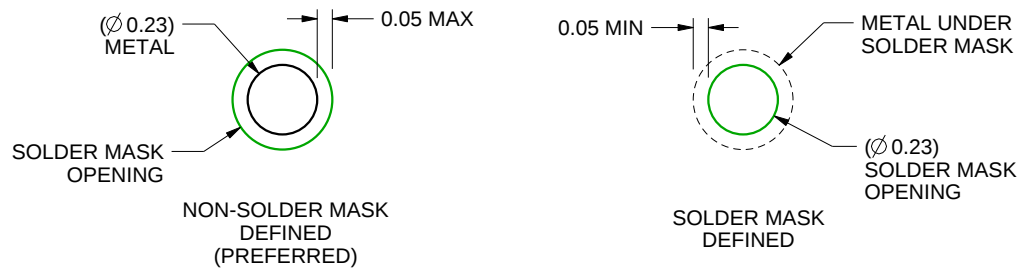
YFP0020

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:25X

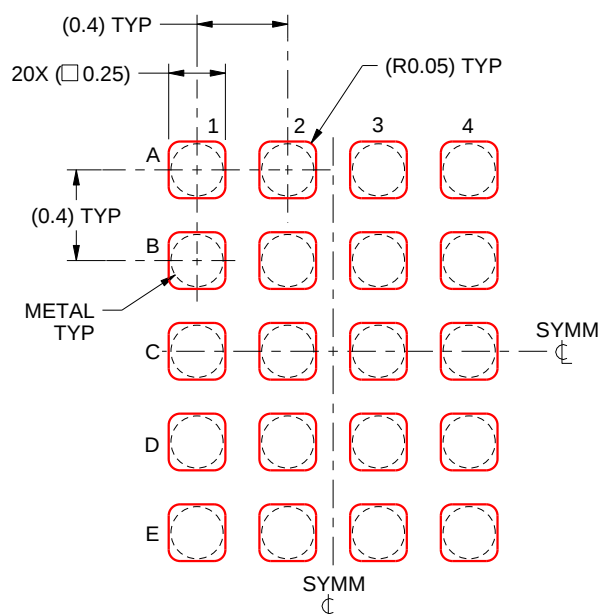


SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
 BASED ON 0.1 mm THICK STENCIL
 SCALE:30X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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